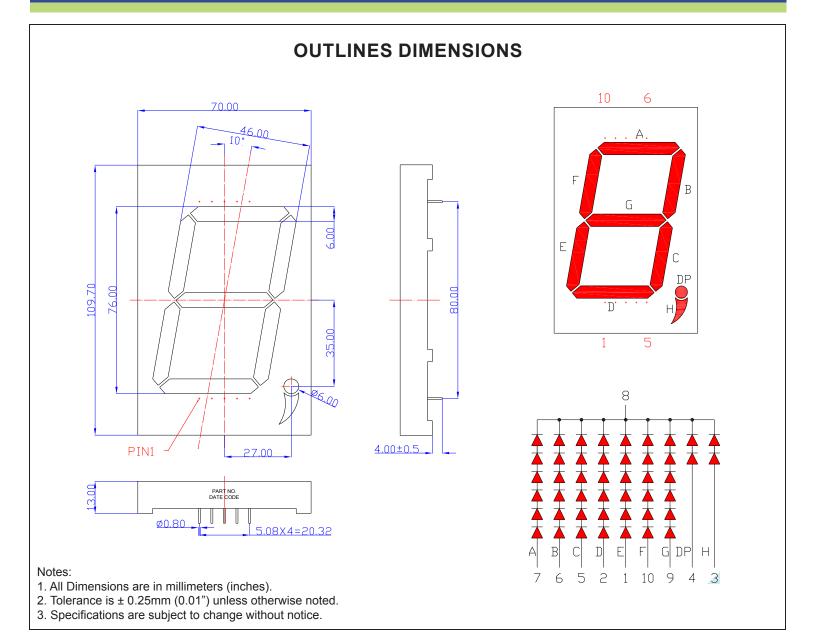


SPECIFICATIONS

CDSC300R2WBF-C



Part Number	Chip Material	Color of Emission	Segment/Face	Description	
CDSC300R2WBF-C	InGaAlP	Red	White / Black	Common Cathode	





ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit			
Power Dissipation	PD	70	mW			
Pulse Forward Current	lfp	90	mA			
Continuous Forward Current	lF	25	mA			
Reverse Voltage Segment	Vr	5	V			
Operating Temperature Range	Topr	-25~+85	°C			
Storage Temperature Range	Тѕтс	-25~+85	°C			
IFP = Pulse Width \leq 10 ms, Duty Ratio \leq 1/10. Soldering Condition: 260 °C/ 5sec						

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

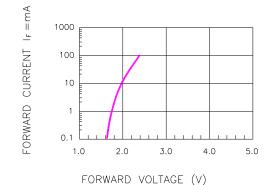
Deremeter	Symbol	Test Condition	Value			Lloit
Parameter			Min	Тур	Max	Unit
Luminous Intensity	lv	l⊧ = 20mA	-	250	-	mcd
Forward Voltage per Segment	Vf	l⊧ = 20mA	-	12	14.4	V
Reverse Leakage Current	lr	V _R = 5V	-	-	10	μA
Peak Wavelength	λP	l⊧ = 20mA	-	632	-	nm
Dominant Wavelength	λD	l⊧ = 20mA	619	624	629	nm
Spectral Radiation Bandwidth	Δλ	l⊧ = 20mA	-	20	-	nm

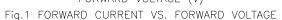


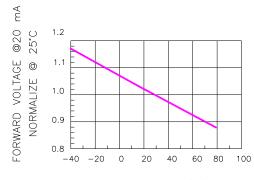


OPTICAL CHARACTERISTIC CURVES

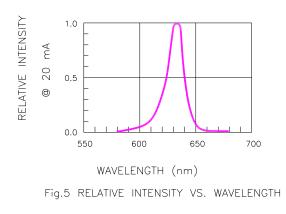
(25 °C Free Air Temperature Unless Otherwise Specified)

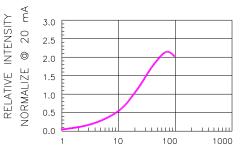




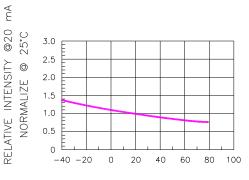


AMBIENT TEMPERATURE(°C) Fig.3 FORWARD VOLTAGE VS. TEMPERATURE

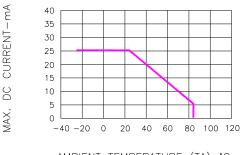




FORWARD CURRENT (mA) Fig.2 RELATIVE INTENSITY VS. FORWARD CURRENT



AMBIENT TEMPERATURE(°C) Fig.4 RELATIVE INTENSITY VS. TEMPERATURE



AMBIENT TEMPERATURE (TA)-°C Fig.6 MAX. ALLOWABLE DC CURRENT VS. AMBIENT TEMPERATURE

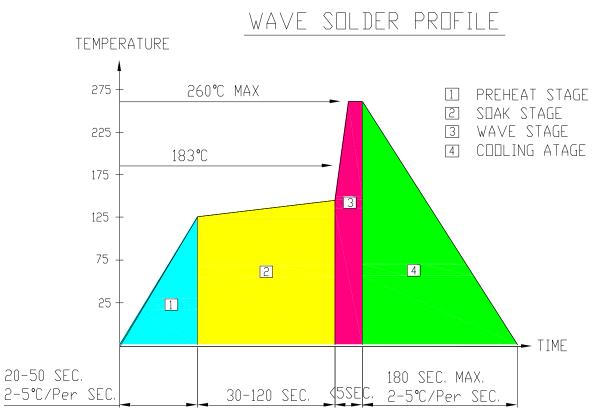


MAX.



SOLDERING CONDITIONS – DISPLAY TYPE LED

• RECOMMEND SOLDERING PROFILE



SOLDERING IRON

Basic spec is \leq 4 sec when 260°C. If temperature is higher, time should be shorter (+10°C→1 sec). Power dissipation of Iron should be smaller than 15W, and temperature should be controllable. Surface temperature of the device should be under 230°C.

REWORK

Customer must finish rework within ≦4 sec under 245°C.

